

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. ASSEMBLE USING ROHS LEAD-FREE SOLDER PROCESS.
- 2. THERMAL VIAS UNDER QFN PACKAGES SHALL BE SOLDER FILLED VIAS.
- 3. ASSEMBLY SHALL CONFORM TO IPC CLASS 2 STANDARDS.
- 3.1 ASSEMBLY SHALL BE PRECEEDED BY FIRST ARTICLE THERMAL PROFILE.
- 3.2 ALL BOARDS MUST UNDERGO 100% VISUAL AND X-RAY INSPECTION. X-RAY FILES MUST BE PROVIDED.

www.openadsb.com Open ADSB Project Sunnyvale, CA USA TITLE ASSEMBLY DRAWING TOP **APPROVALS** DATE OpenADSB USB Stick DWN B Kuschak 04/14/12 DWG NO. CKD SIZE REV SHEET APVR 1 OF 1